

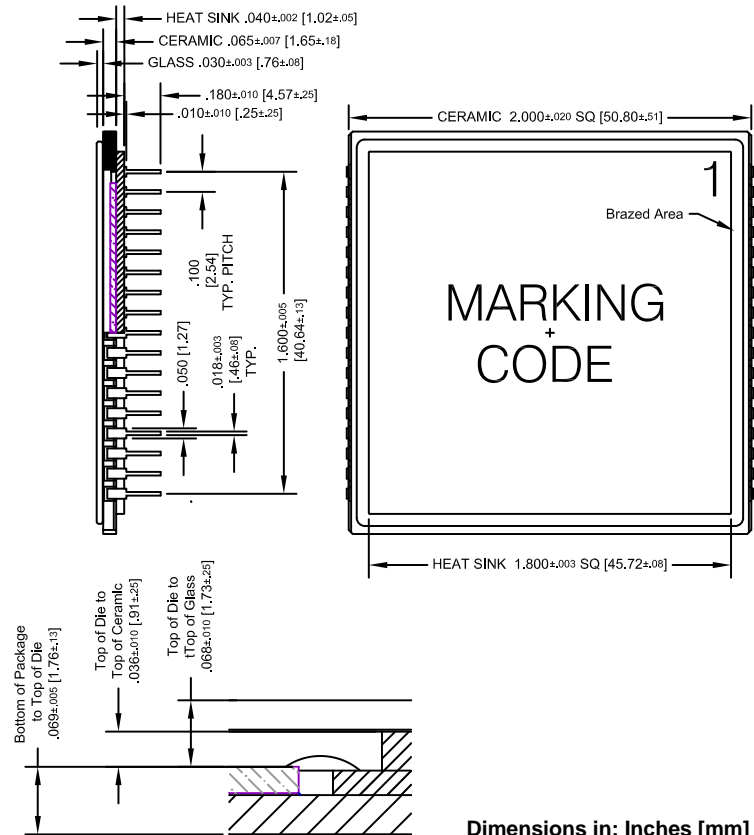
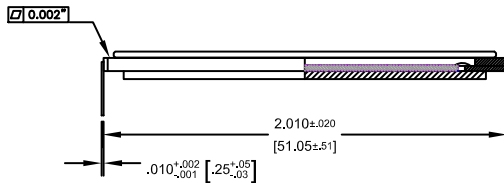
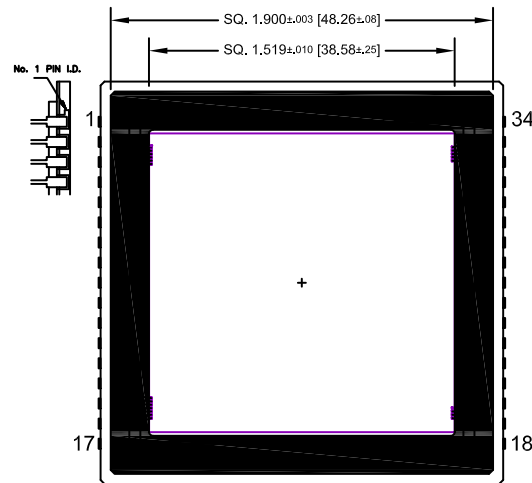
CERAMIC DIP 34, 50.8x50.8
CASE 125BL
ISSUE O

DATE 03 JUL 2014

NOTES:

1. Die is visually aligned within 1 degree of any package cavity edge.
2. Die surface flatness: 0.002" Max T.I.R.

SHOWN WITH SEALED COVER GLASS



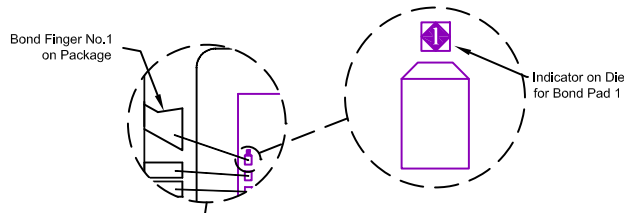
Dimensions in: Inches [mm]

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DESCRIPTION:	CERAMIC DIP 34, 50.8x50.8	PAGE 1 OF 2

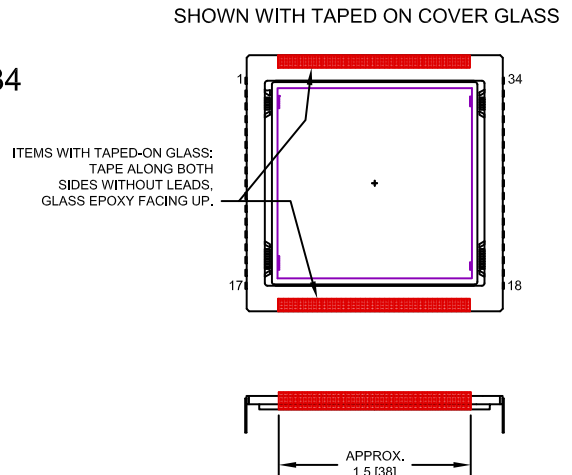
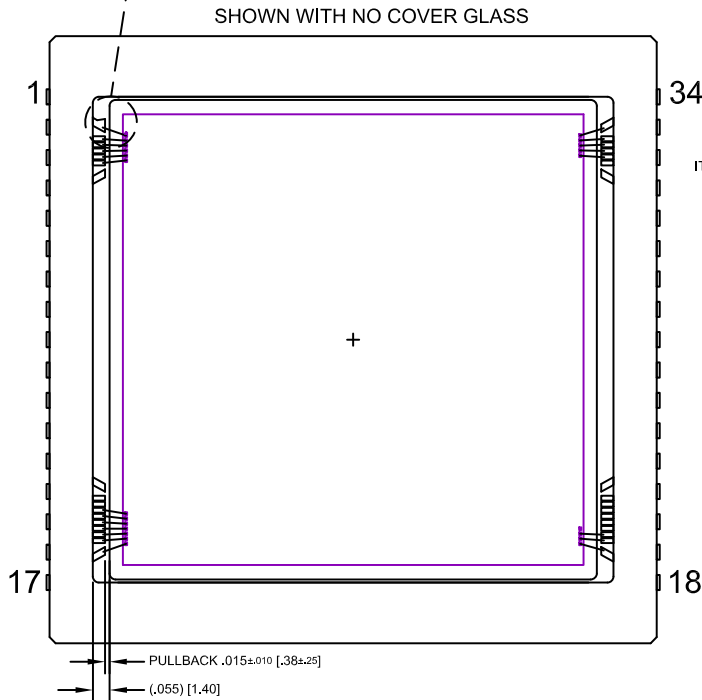
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- NOTES:
1. FOR SINGULATION PURPOSES: DIE ON WAFER ARE STEPPED (x) 38.60 mm, (y) 37.76 mm. ASSUMING 50 MICRON KERF, SINGULATED DIE ARE APPROXIMATELY 38.55 mm X 37.71 mm.
 2. WIRE LOOP HEIGHT: 0.014" +/- 0.003"
 3. TAPE USED TO TEMPORARILY HOLD ON GLASS IS PERMACEL P224 OR EQUIVALENT.



Dimensions in: Inches [mm]

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